

Horizontal Headers with Holddowns, Unshrouded, Double Row, Surface-Mount (Continued)

1.00 [.039] Mating Pin-to-PC Board Dimension

Two metallic spring hold-downs on each end of surface-mount right-angle header work with plastic location features for PC board retention prior to solder flow

Material and Finish:

Housing—Black polyphenylene sulfide, 94V-0 rated

Posted Contacts—Copper alloy, duplex plated gold flash over 0.00076 [.00030] min., palladium-nickel on contact area, 0.00508 [.000200] min., tin-lead on solder area, with entire contact underplated 0.00130 [.00051] min., nickel

Related Product Data:

PC Board Layout—page 11

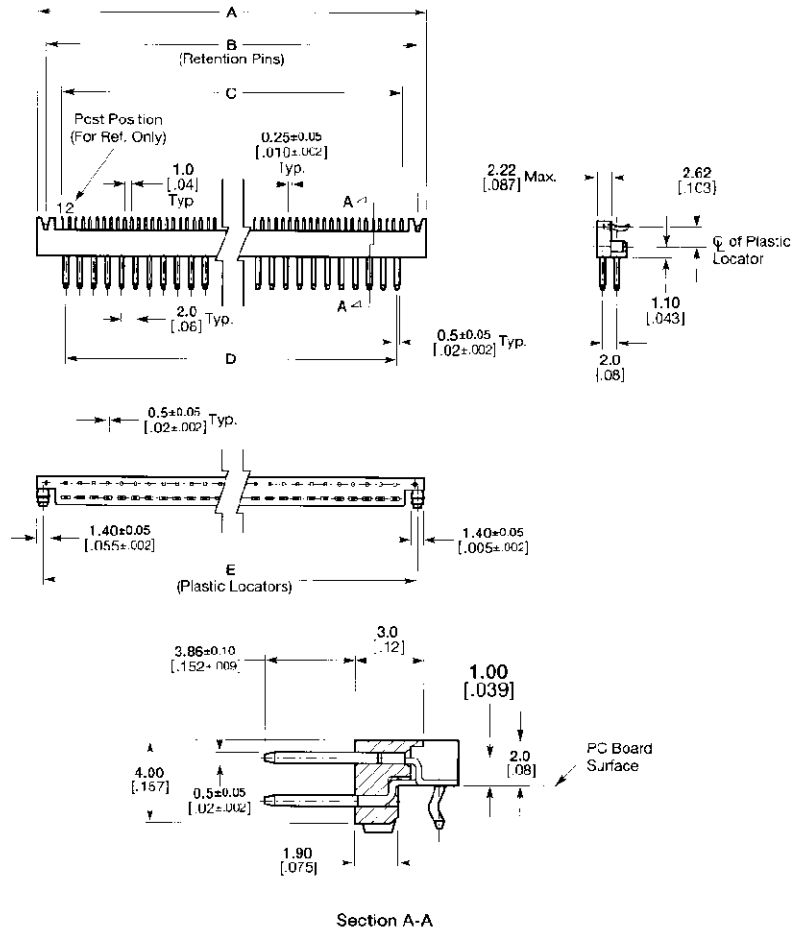
Mateable Receptacles—pages 12, 13, 16 and 17

Performance Specifications—page 20

Technical Documents (page 20):

AMP Product Specification
108-51004

Packaging Method—Tray



No. of Positions	Dimensions					Header Part Numbers	Posts Omitted
	A	B	C	D	E		
50	56.03	54.15	49.0	48.0	54.79	84108-2	25, 45, 46
	2.206	2.132	1.93	1.89	2.157		
50	56.03	54.15	49.0	48.0	54.79	84108-7	5, 6, 26
	2.206	2.132	1.93	1.89	2.157		
50	56.03	54.15	49.0	48.0	54.79	1-84108-1*	25, 45, 46
	2.206	2.132	1.93	1.89	2.157		

*Packaged in tube